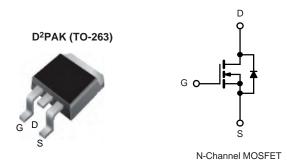


N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	$(\Omega) \qquad I_{D}(A)^{a,c} Q_{g}$			
40	0.0017 at V _{GS} = 10 V	150	120 nC		
	0.0025 at V _{GS} = 4.5 V	135	120110		



FEATURES

- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested

APPLICATIONS

- Synchronous Rectification
- Power Supplies

Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	40	N/	
Gate-Source Voltage		V _{GS}	± 25	V
	T _C = 25 °C		150 ^{a, c}	
Continuous Drain Current (T 175 °C)	T _C = 70 °C		120 ^c	
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	I _D	29 ^b	_
	T _A = 70 °C		23 ^b	A
Pulsed Drain Current		I _{DM}	380	
valanche Current Pulse		I _{AS}	80	
Single Pulse Avalanche Energy L = 0.1 mH		E _{AS}	320	mJ
	T _C = 25 °C	I _S	110 ^{a, c}	Α
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	2.6 ^b	A
	T _C = 25 °C		312 ^a	
Maximum David Disais ation	T _C = 70 °C	P	200	10/
Maximum Power Dissipation	T _A = 25 °C	P _D	3.13 ^b	W
	T _A = 70 °C		2.0 ^b	
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.33	0.4	C/W	

Notes:

a. Based on T_C = 25 °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 110 A.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter Static	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 µA	45			V	
V _{DS} Temperature Coefficient	vDs ∆V _{DS} /T _J	VGS - 0 V, ID - 200 µA	40	41		w mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 8			
Gate-Source Threshold Voltage	, ,	V _{DS} = V _{GS} , I _D = 250 μA	1.2	- 0	2.5	V	
ő	V _{GS(th)}	$V_{DS} = V_{GS}, V_{DS} = 200 \mu A$ $V_{DS} = 0 V, V_{GS} = \pm 20 V$	1.2		-	-	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$ $V_{DS} = 40 V, V_{GS} = 0 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			1 10 μA		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, V_{GS} = 10 V	120			Α	
		V _{GS} = 10 V, I _D = 30 A		0.0017		<u> </u>	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 20 A		0.0025		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A		180		S	
Dynamic ^b						1	
Input Capacitance	C _{iss}			9000		pF	
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		650			
Reverse Transfer Capacitance	C _{rss}			450			
Total Gate Charge	Qg			120	180	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 20$ V, $V_{GS} = 10$ V, $I_{D} = 20$ A		30			
Gate-Drain Charge	Q _{gd}			16			
Gate Resistance	R _g	f = 1 MHz		0.85	1.3	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = 20 V, R_{L} = 1.0 Ω		11	17	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20$ Å, V_{GEN} = 10 V, R_g = 1 Ω		77	115		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			102	155	ns	
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		62	95	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		180	270		
Fall Time	t _f			60	90		
Drain-Source Body Diode Characteristic	s					1	
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			110	A	
Pulse Diode Forward Current ^a	I _{SM}				200	A	
Body Diode Voltage	V _{SD}	I _S = 20 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			50	75	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	-		70	105	nC	
Reverse Recovery Fall Time	t _a	— I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		30			
Reverse Recovery Rise Time	t _b			20		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

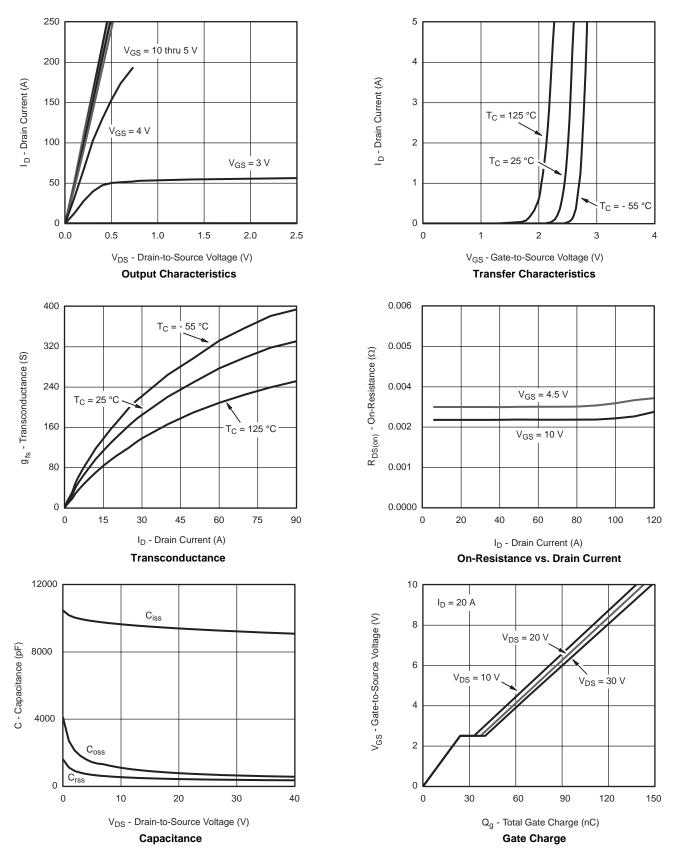
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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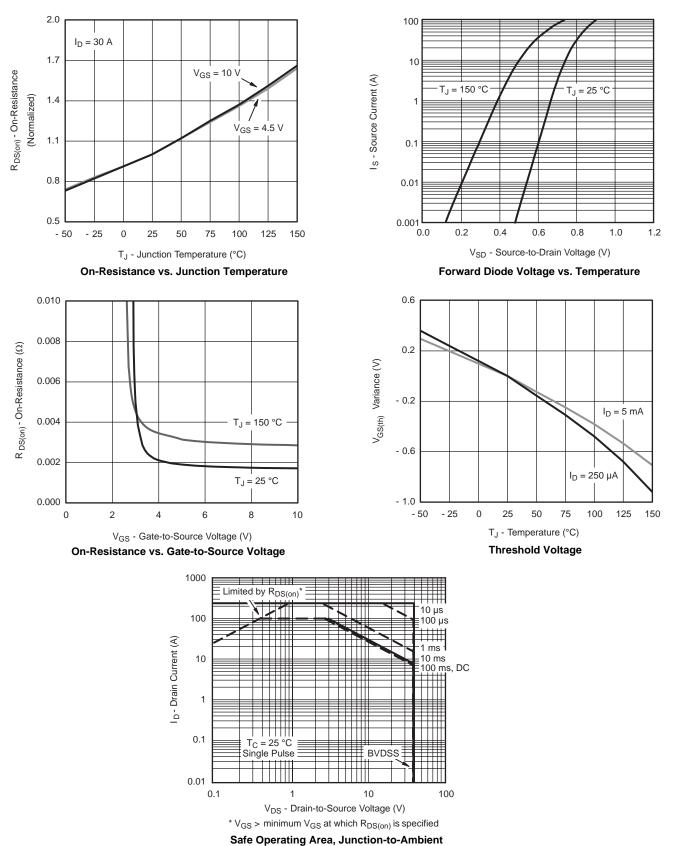
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



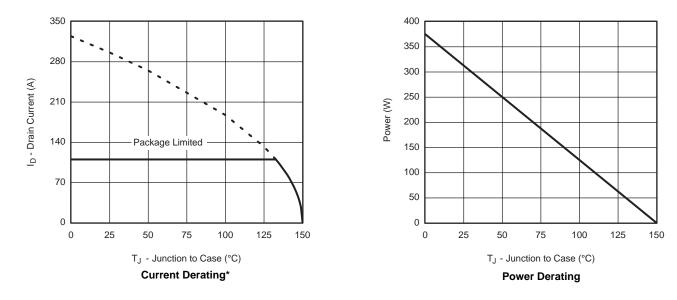
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

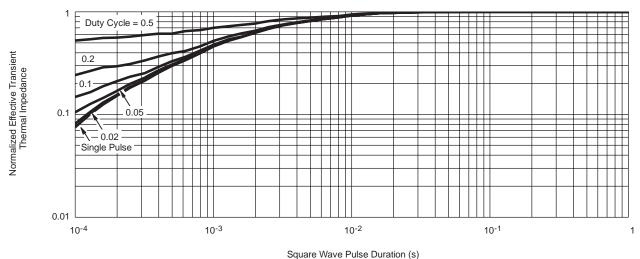






TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

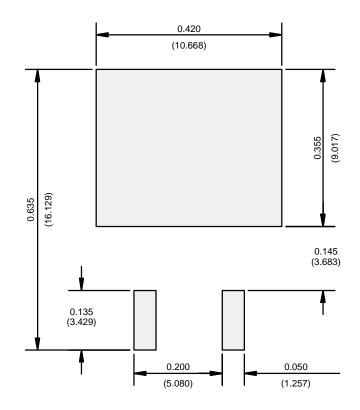
* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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